

IN THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the present application:

Claims 1-91 (Previously Withdrawn)

92. (Currently Amended) A method of preparing a substrate for adherence of [[an adhesive]] a material thereto, the substrate having a surface, the method comprising the steps of:

- a) generating an active zone using an electromagnetic radiation source; and
- b) exposing the surface of said substrate to the active zone, whereby the surface of the substrate is chemically modified for adhering a material [[including an adhesive]] onto said substrate by exposure to the active zone, wherein the substrate is exposed to electromagnetic radiation in the active zone including ultraviolet radiation having a wave length in the range of about 150 nanometers to 400 nanometers and wherein the step of exposing occurs at substantially ambient pressure.

93. (Previously Presented) The method of claim 92, wherein the substrate includes a polymer.

94. (Previously Presented) The method of claim 92, wherein said substrate includes a sole of a shoe.

95. (Previously Presented) The method of claim 92, wherein said substrate includes a composite used in aircraft and space vehicle fabrication.

96. (Previously Presented) The method of claim 92, wherein said substrate includes a component used in automobile manufacturing.

97. (Previously Presented) The method of claim 92, wherein said substrate includes a well-plate, wherein said well-plate is used for biochemical analysis.

98. (Previously Presented) The method of claim 92, wherein said electromagnetic radiation includes infra-red radiation.

99. (Cancelled)

100. (Cancelled)

101. (Previously Presented) The method of claim 92, wherein the intensity of said electromagnetic radiation at the surface of the substrate ranges from about 2.0 joules per square centimeter to about 5,000 joules per square centimeter.

102. (Previously Presented) The method of claim 92, wherein the intensity of said electromagnetic radiation at the surface of the substrate ranges from about 10 joules

per square centimeter to about 1000 joules per square centimeter.

103. (Currently Amended) The method of claim 92, wherein the ~~[[steps]]~~ step of exposing includes conveying the substrate through said active zone using a conveyor system whereby the substrate is exposed to the active zone for a residence time.

104. (Previously Presented) The method of claim 103, wherein the residence time is in a range of from about 0.1 seconds to about 10 seconds.

105. (Previously Presented) The method of claim 103, wherein the residence time is in a range of from about 0.2 seconds to about 5 seconds.

106. (Original) The method of claim 103, wherein the conveyor system further includes a conveyor belt for carrying the substrate.

107. (Currently Amended) The method of claim 103, further comprising the step of evacuating the active zone in a location adjacent to the conveyor system.

108. (Previously Presented) The method of claim 92, further comprising the step of exposing the substrate to a discharge from an electro-ionization device.

109. (Original) The method of claim 108, wherein the electro-ionization device is located in the active zone.

110. (Currently Amended) The method of claim 108, further comprising the step of circulating a gas proximate said electro-ionization device so that said gas flows over the electro-ionization device onto the substrate.

111. (Currently Amended) The method of claim 103, [[further comprising]] wherein the step of exposing includes exposing the surface of the substrate to infra-red radiation generated by an infra-red radiation source, wherein the surface of the substrate is heated by exposure to the infra-red radiation generated by the infra-red radiation source.

112. (Currently Amended) The method of claim 111, wherein the step of exposing includes exposing the surface of the substrate to the infra-red radiation [[occurs]] prior to [[the step of]] exposing [[said]] the surface of the substrate to the [[active zone]] ultraviolet radiation.

113. (Previously Presented) The method of claim 92, further comprising the step of directing a gas over the surface of the substrate exposed to the active zone.

114. (Previously Presented) The method of claim 113, wherein the gas to be injected over the surface of the substrate exposed to the active zone includes a gas selected from the group consisting of carbon tetrachloride, chloroform, halogen functionality compounds, oxygen functionality compounds, water vapor, oxygen, air,

silanes, amine functionality compounds, ammonia and nitrogen.

115. (Currently Amended) A method of preparing a substrate for adherence of ~~[[an adhesive]]~~ a material thereto, the substrate having a surface, the method comprising the steps of:

a) generating an active zone at substantially atmospheric pressure using an electromagnetic radiation source, wherein electromagnetic radiation generated by said ~~[[electro-magnetic]]~~ electromagnetic radiation source ~~[[is]]~~ includes ultraviolet radiation having a wave length in the range of about 150 nanometers to ~~[[250]]~~ 400 nanometers, and

b) exposing the surface of the substrate to the electromagnetic radiation, wherein the intensity of said electromagnetic radiation at the surface of the substrate ranges from about ~~[[10]]~~ 0.1 joules per square centimeter to about ~~[[1000]]~~ 50,000 joules per square centimeter, wherein the material is selected from the group consisting of a glue, a coating, an adhesive, a paint and a resinous compound, whereby the ~~[[polymer]]~~ surface of the substrate is chemically modified for adhering ~~[[a]]~~ the material ~~[[including an adhesive]]~~ onto the surface of the polymer substrate by exposing the surface to said active zone; the step of exposing including conveying the substrate through said active zone, whereby the surface of the substrate is exposed to the active zone for a residence time, wherein the residence time is in a range of from about 0.2 seconds to about 5 seconds.

Claims 116-118 (Previously Cancelled)

119. (Previously Presented) The method of claim 115, wherein the substrate is includes of a synthetic polymer.

120. (Previously Presented) The method of claim 115, wherein the substrate includes a naturally-occurring polymer.

121. (Currently Amended) A method of preparing a polymer substrate for adherence of an adhesive a material thereto, the substrate having a surface, the method comprising the steps of:

a) providing a conveyor system including a conveyor and an electromagnetic radiation source;

b) generating an active zone proximate the conveyor at substantially atmospheric pressure using the electromagnetic radiation source, wherein electromagnetic radiation generated by the electromagnetic radiation source is includes ultraviolet radiation having a wave length in the range of about 150 nanometers to 250 400 nanometers, and

c) exposing the surface of the surface of the substrate to the electromagnetic radiation generated by the electromagnetic radiation source, wherein the intensity of said electromagnetic radiation at the surface of the substrate ranges from about 2.0 joules per square centimeter to about 5,000 joules per square centimeter, whereby the surface of the polymer substrate is chemically modified for adhering a to improve adherence of the material including an adhesive onto the surface of the polymer

substrate by exposing the surface to said active zone; the step of exposing including conveying the [[polymer]] substrate through said active zone, whereby the surface of the [[polymer]] substrate is exposed to the active zone for a residence time, and wherein the residence time is in a range of from about 0.2 seconds to about 5 seconds.

122. (Currently Amended) The method of claim 121, further comprising the step of adhering a material [[including an adhesive]] onto the surface of the [[polymer]] substrate for the purposed of bonding the material to the substrate, wherein the material is selected from the group consisting of a glue, a coating, an adhesive, a paint and a resinous compound.

123. (Previously Presented) The method of claim 122, further comprising the step of evacuating the active zone adjacent to the conveyor system.

124. (Currently Amended) The method of claim 121, further comprising the [[step]] steps of exposing the surface of the substrate to [[a further radiation]] an ionized discharge generated by an electro-ionization device; and circulating a [[first]] gas stream past the electro-ionization device so that the first gas stream flows past the electro-ionization device and onto the surface of the substrate; wherein the [[further radiation is infra-red radiation]] step of providing includes providing a conveyor system further including an electro-ionizing device.

125. (New) The method of claim 124, further comprising the step of exposing the

substrate to additional radiation, wherein the radiation is infra-red radiation and the step of providing includes providing a conveyor system further including a source of infra-red radiation.

126. (New) The method of claim 125, further comprising the step of evacuating the active zone adjacent to the conveyor system.

127. (New) The method of claim 125, further comprising the step of adhering a material onto the surface of the polymer substrate for the purposed of bonding the material to the substrate, wherein the material is selected from the group consisting of a glue, a coating, an adhesive, a paint and a resinous compound.

128. (New) A method of chemically modifying a substrate for adherence of a material thereto, the substrate having a surface, the method comprising the steps of:

- a) generating an active zone using an electromagnetic radiation source; and
- b) exposing the surface of the substrate to the active zone at substantially ambient pressure, wherein the surface of the substrate is exposed to electromagnetic radiation in a range from about 0.1 joules per square centimeter to about 50,000 joules per square centimeter, said electromagnetic radiation including ultraviolet radiation having a wave length in the range of from about 150 nanometers to 400 nanometers, whereby the substrate is exposed to electromagnetic radiation sufficient to chemically modify the surface of the substrate so that adherence of the material onto the surface of the substrate is enhanced by increasing the wettability of the surface.

129. (New) The method of claim 128, wherein the material is selected from the group consisting of a glue, a coating, an adhesive, a paint and a resinous compound.

130. (New) The method of claim 128, wherein the substrate includes a polymer.

131. (New) The method of claim 128, wherein the step of exposing includes conveying the substrate through said active zone, whereby the substrate is exposed to the active zone for a residence time, wherein the residence time is in a range of from about 0.2 seconds to about 5 seconds.

132. (New) The method of claim 131, further comprising the step of adhering a material onto the surface of the polymer substrate for the purposed of bonding the material to the substrate wherein the material is selected from the group consisting of a glue, a coating, an adhesive, a paint and a resinous compound.

133. (New) The method of claim 131, further comprising the steps of exposing the surface of the substrate to an ionized discharge generated by an electro-ionization device; and circulating a first gas stream past the electro-ionization device so that the first gas stream flows past the electro-ionization device and onto the surface of the substrate.

134. (New) The method of claim 131, further comprising the step of evacuating the

active zone adjacent to the conveyor system.

135. (New) The method of claim 131, further comprising the step of exposing the substrate to additional radiation, wherein the radiation is infra-red radiation.